



CLGA

CERAMIC LAND GRID ARRAY

SPECIFICATION FORM

NAME _____

TITLE _____

COMPANY _____

PHONE _____

EMAIL _____

FAX _____

1. Quantity Required _____

8. Need Delivery By _____

2. Body Size _____ x _____ mm

9. Ceramic Thickness

1.0mm (Standard)

1.5mm

3.0mm

other _____

3. Number I/O Pads _____

4. Pitch 1.27mm 1.0mm other _____

5. Pad Material

Palladium Silver (Standard)

5mil Raised Pad Sn62 (5mil high)

Ball Attach by Customer

10. Application

Hand Insertion into Socket

Ball Attach by Customer

other _____

6. Pad Diameter

Standard

other _____ mm

11. Circuit

Daisy Chain Required

All Pads Shorted

All Pads Isolated

Any Available

7. Markings

None Standard

Part Number Configuration

CLGA	625	T	1.27	- DC61	A	3
<u>Substrate</u>	<u>I/O</u>	<u>Packaging</u>	<u>Pitch</u>	<u>Circuit</u>	<u>Options</u>	<u>Substrate</u>
Ceramic		T = Trays	mm	DC = Daisy Chain Pads BUS = All Pads Shorted ISO = All Pads Isolated	Blank = Standard for Socket E = Raised Pad 5mil B = Ball Attach by Customer X = Customer Spec	Blank = 1.0mm thick (Standard) 2 = 1.5mm thick 3 = 3mm thick

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F
O**

CLGA - Ceramic Land Grid Arrays for socket insertion and Ball Attach
Available in a variety of configurations and pad heights.
Contact TopLine for details.